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(54) **Title:** INGOT PULLER APPARATUS THAT INCLUDE A DOPING CONDUIT WITH A POROUS PARTITION MEMBER FOR SUBLIMING SOLID DOPANT

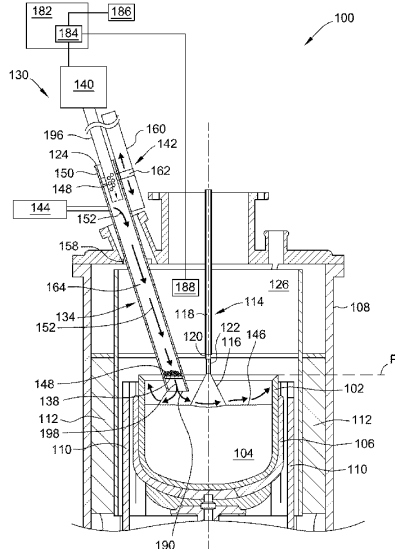


FIG. 1

(57) **Abstract:** Ingot puller apparatus for preparing silicon ingots that include a dopant feed system are disclosed. The dopant feed system include a dopant conduit having a porous partition member disposed across the dopant conduit. Solid dopant falls onto the partition member where it sublimes. The sublimed dopant is carried by inert gas through the partition member to contact and dope the silicon melt.

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